## Lam Research Corporation To Show Process Integration, Productivity, And Capability Advances At SEMICON® Japan 99

Lam Research Corporation To Show Process Integration, Productivity, And Capability Advances At SEMICON<sup>®</sup> Japan 99 FREMONT, Calif., November 30, 1999 - Lam Research Corporation (Nasdaq: LRCX), a leading supplier of front-end wafer fabrication equipment to the worldwide semiconductor industry, today announced that it will present process integration, productivity, and capability advances at SEMICON Japan. Lam will show its Exelan dielectric etch and Teres CMP systems. The show runs December 1-3, 1999, at the Makuhari Messe Convention Center in Makuhari, Japan. Lam will exhibit at Booth 1-A903 with Novellus Systems, Inc.

Multimedia programs will present process and productivity solutions for all Lam products and will include the Novellus Speed and Inova deposition systems that are part of the Novellus/Lam Damascus Alliance.

According to Yoichi Isago, president of Lam Research Co., Ltd., "SEMICON Japan is an important show for Lam, particularly following the doubling of our overall etch market share in Japan in the past year. In addition to providing productivity improvement support, we will assist our Japanese customers in leveraging the extendibility to 0.13 micron and below of Lam's etch systems."

Lam's versatile, low cost of ownership (CoO) Exelan dual frequency dielectric etch system is optimized for dual damascene patterning and a broad range of critical and noncritical etch processes. Exelan ensures leading capability and productivity while providing the industry's lowest CoO per wafer.

The Teres CMP system, integrated with the Synergy Integra clean module, provides next-generation Linear Planarization Technology (LPT<sup>TM</sup>). Teres provides superior process control for a broad process window, minimizes dishing and erosion for copper polish, enables direct-polish STI, and sets new standards for reliability in the field.

Lam Research Corporation is a leading supplier of front-end wafer fabrication equipment and services to the world's semiconductor industry. The company's common stock trades on the Nasdaq National Market under the symbol LRCX. Lam's World Wide Web address is <u>http://www.lamrc.com</u>.

"Safe Harbor" Statement Under the Private Securities Litigation Act of 1995: This press release contains certain forward-looking statements which are subject to the Safe Harbor provisions created by the Private Securities Litigation Reform Act of 1995. Such forward-looking statements relate to anticipated performance, acceptance, capabilities, applications, and competitiveness of the company's products and market transition to new processes. Such statements are based on current expectations and are subject to risks, uncertainties, and changes in condition, such as may arise from introduction of such products into production and their ability to perform consistent with current expectation, and other risks detailed in documents filed with the Securities and Exchange Commission, including specifically the report on Form 10-K for the year ended June 30, 1999, and the Form 10-Q for the quarter ended September 30, 1999. The company undertakes no obligation to update the information in this Press Release.

https://newsroom.lamresearch.com/1999-11-30-Lam-Research-Corporation-To-Show-Process-Integration,-Productivity,-And-Capability-Advances-At-SEMICON-R-Japan-99